

Abstract

A leadframe is disclosed. The leadframe comprises a frame characterized by a substantially rectangular outline, a die paddle with a receiving surface, and a plurality of support members that connect the frame to the die paddle. The leadframe further comprises a plurality of leads connected to the frame, that will eventually serve to electrically connect an integrated circuit mounted on the die paddle to an external electrical device. The die paddle lies in a lower horizontal plane. A plurality of support members connect the frame with the die paddle. As projected on to a vertical plane that is perpendicular to the side of the frame to which a support member is attached, the offset angle between the support member and a vertical axis is less than 45 degrees.